deava®

Technical Data Sheet

deawa[®] DW-5213 release agent Issue Date: 01/FEB/2019

Product Introduction

Deawa[®] DW-5213 Mold Release Agent is a semi-permanent release agent for mold demoulding, it has shown great effect in the high-demanding release applications and could be applied to general mold composite parts which in unsaturated/polyester resin,epoxy resin and etc.,but not available for some special composite products,Pleas contact Deawa to learn more details.

Properties

No chlorine solvent Smooth surface, easy to separate Wide application—applied to most polyester materials Dried and solidified under room temperature No transfer No residual

Physical and Chemical Properties of the Material

Appearance:	Clear Liquid
Odor:	Hydrocarbon
Solvent:	Synthetic Paraffin Hydrocarbon/Light Fat Solvent Naphtha/Polysiloxane
Relative Density:	0.711+/-0.02
Flash Point:	31°C (88°F)
Shelf Life:	1 year
Cured Thermal Stability:	≤310 ℃
Application Temperature:	13 to 135°C (55 to 275°F)

Notice: Sensitive to humidity, be safely sealed when not being used. Keep it in well ventilate condition when being used.

Mold Preparation

Cleaning:

In order to get the best effect, Deawa[®] DW-5213 mold Release agent should be applied to a clean and dry mold. All traces of prior release on the mold surface must be removed.

Sealing:

New mold and repaired mold can be applied deawa[®] sealer to get better release effect and product appearance smoothness. Please refer to the instruction of deawa[®] sealer. Or follow the mold supplier's instruction.

Application of release agent (refer to the product safety data before use) :

Brush or wipe Deawa[®] DW-5213 with a a clean dust-free cloth on mold surfaces at room temperature less than 60° C in a well ventilated area.(can't use non-woven, because Deawa[®] DW-5213 solvents dissolve the adhesive of non-woven.) It will be better to brush or wipe from the side of the mold to the other side orderly.
Use a new clean dry cloth, from outside to inside circularly wipe the surface before the wet agent evaporate, until the mold surface is dry and clear. Then the first layer of release agent film is coated on mold surface, it should be a layer of smooth, continuous film.

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3. After solvent evaporation, repeat step1 and step2 to apply the 2nd layer up. Generally apply 2 to 5 base layers , each layer needs 10 to 15 minutes to solvent evaporation, the film should be dry and not sticky.

4. Allow the final coat to cure for 20 to 30 minutes at room temperature. Note the lower temperature will cause more cure time. Avoid use the mold after just wipe release agent, the release agent film should be solidified completely to be used in subsequent process.

5. When any release difficulty is detected, can choose to re-coat the whole mold again, or only the area with problems. If the mold temperature is higher than 135 ° C, make sure Deawa[®] DW-5213 is dry thoroughly before reused.

Attention:

Before shutting a close mold (such as rotational mold), be sure all the solvent volatilized totally, especially pits and holes on the surface of the mold. Oil-free compressed air can help eliminate the solvent retention. Flammability/store

Deawa® DW-5213 contain flammable solvents. This product should be used in a well ventilated area. Stored in a dry, cool place. When not in use, should maintain the cover sealed.